

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3082539

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MIHIR TENDULKAR	09/16/2014
RANDALL HIGUCHI	10/23/2014
CHIEN-LAN HSUEH	10/25/2014

RECEIVING PARTY DATA

Name:	Intermolecular, Inc.
Street Address:	3011 N. First Street
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	KABUSHIKI KAISHA TOSHIBA
Street Address:	1-1, SHIBAURA 1-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8001
Name:	SANDISK 3D LLC
Street Address:	951 SANDISK DRIVE
City:	MILPITAS
State/Country:	CALIFORNIA
Postal Code:	95034

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13835256

CORRESPONDENCE DATA

Fax Number: (408)582-5401

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4085825533

Email: patents@intermolecular.com

Correspondent Name: INTERMOLECULAR, INC.

PATENT

Address Line 1: 3011 N. FIRST STREET
Address Line 4: SAN JOSE, CALIFORNIA 95134

ATTORNEY DOCKET NUMBER:	IM0851_US
NAME OF SUBMITTER:	MANU KASHYAP
SIGNATURE:	/Manu Kashyap/
DATE SIGNED:	10/27/2014

Total Attachments: 3

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ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

Metal Aluminum Nitride Embedded Resistors for Resistive Random Memory Access Cells (Atty. Docket No. IM0851_US) for which we have executed an application for a United States Letters Patent filed on March 15, 2013 having the application number 13/835,256

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventors hereby:

- 1) Sell, assign and transfer to **Intermolecular, Inc.**, a **Delaware** corporation having a place of business at **3011 N. First Street, San Jose, California 95134 U.S., Kabushiki Kaisha Toshiba doing business at 1-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8001, Japan and SanDisk 3D LLC doing business at 951 SanDisk Drive, Milpitas, CA 95034 USA**, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

- 1) Signature: _____ Date: _____
Typed Name: MIHIR TENDULKAR
- 2) Signature: _____ Date: _____
Typed Name: RANDALL HIGUCHI
- 3) Signature: Chien-Lan HSUEH Date: 10/25/14
Typed Name: CHIEN-LAN HSUEH

ASSIGNMENT OF PATENT APPLICATION

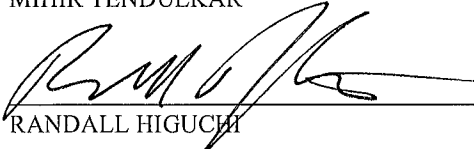
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- | | | |
|----|---|-----------------------|
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Typed Name: MIHIR TENDULKAR | Date: _____ |
| 2) | Signature:  _____
Typed Name: RANDALL HIGUCHI | Date: <u>10/23/14</u> |
| 3) | Signature: _____
Typed Name: CHIEN-LAN HSUEH | Date: _____ |

ASSIGNMENT OF PATENT APPLICATION

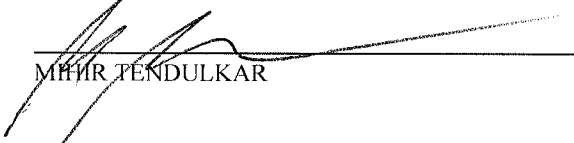
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